

Product Information

DOW CORNING

Encapsulants

Dow Corning® 184 Silicone Elastomer

2-part, 10:1 mix, transparent encapsulant with good flame resistance

FEATURES

- Flowable
- RT and heat cure
- High tensile strength
- Same as Sylgard 182 but with RT cure capability
- UL and Mil Spec tested

BENEFITS

- Rapid, versatile cure processing controlled by temperature
- High transparency allows easy inspection of components
- Can be considered for uses requiring UL and Mil Spec requirements

POTENTIAL USES

- General potting applications
- Power supplies
- Connectors
- Sensors
- Industrial controls
- Transformers
- Amplifiers
- High voltage resistor packs
- Relays
- Adhesive/encapsulant for solar cells
- Adhesive handling beam lead integrated circuits during processing

APPLICATION METHODS

- Automated metered mixing and dispensing
- Manual mixing

TYPICAL PROPERTIES

Specification Writers: Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

Property	Unit	Value
Viscosity (Part A or Base)	cP	5225
	mPa-sec	5225
	Pa-sec	5.2
Viscosity (Mixed)	cP	3500
	mPa-sec	3500
	Pa-sec	3.5
Specific Gravity (Uncured Part A or Base)	-	1.03
Specific Gravity (Cured)	-	1.04
Working Time at 25°C (Pot Life - hours)	hr	>2
Cure Time at 25°C	hrs	48
Heat Cure Time @ 100°C	minutes	35
Heat Cure Time @ 125°C	minutes	20
Heat Cure Time @ 150°C	minutes	10
Tensile Strength	psi	895
	MPa	6.2
	kg/cm ²	62
Elongation	%	85
Tear Strength (Die B)	ppi	5
	N/cm	2
Durometer Shore A	-	48
Dielectric Strength	volts/mil	350
	kV/mm	14
Volume Resistivity	ohm*cm	2.9E+14

DESCRIPTION

Dow Corning® silicone encapsulants are supplied as two-part liquid component kits. When liquid components are thoroughly mixed, the mixture cures to a flexible elastomer, which is well suited for the protection of electrical/electronic applications. Dow Corning silicone encapsulants cure without exotherm at a constant rate regardless of sectional thickness or degree of confinement. Dow Corning silicone elastomers require no post cure and can be placed in service immediately following the completion of the cure schedule. Standard silicone encapsulants require a surface treatment with a primer in addition to good cleaning for adhesion while primerless silicone encapsulants require only good cleaning.

MIXING AND DE-AIRING

The 10:1 mix ratio these products are supplied in gives one latitude to tune the modulus and hardness for specific application needs and production lines. In most cases de-airing is not required.

PREPARING SURFACES

In applications requiring adhesion, priming will be required for the silicone encapsulants. See the Primer Selection Guide for the correct primer to use with a given product. For best results, the primer should be applied in a very thin, uniform coating and then wiped off after application. After application, it should be thoroughly air dried prior to application of the silicone elastomer. Additional instructions for primer usage can be found in the information sheets specific to the individual primers.

PROCESSING/CURING

Thoroughly mixed Dow Corning silicone encapsulant may be poured/dispensed directly into the container in which it is to be cured. Care should be taken to minimize air entrapment. When practical, pouring/dispensing should be done under vacuum, particularly if the component being potted or encapsulated has many small voids. If this technique cannot be used, the

TYPICAL PROPERTIES, continued

Property	Unit	Value
Dielectric Constant at 100 Hz	-	2.72
Dielectric Constant at 100 kHz	-	2.68
Dissipation Factor at 100 hz	-	0.00257
Dissipation Factor at 100 kHz	-	0.00133
Mil Specification	NA	Mil Spec
Agency Listing	-	UL 94V-0
Shelf Life at 25°C	months	24
Refractive Index @ 589 nm	-	1.4118
Refractive Index @ 632.8 nm	-	1.4225
Refractive Index @ 1321 nm	-	1.4028
Refractive Index @ 1554 nm	-	1.3997

unit should be evacuated after the silicone encapsulant has been poured/dispensed. Dow Corning silicone encapsulants may be either room temperature (25°C/77°F) or heat cured. Room temperature cure encapsulants may also be heat accelerated for faster cure. Ideal cure conditions for each product are given in the product selection table. Two-part condensation cure encapsulants should not be heat accelerated above 60°C (140°F).

POT LIFE AND CURE RATE

Cure reaction begins with the mixing process. Initially, cure is evidenced by a gradual increase in viscosity, followed by gelation and conversion to a solid elastomer. Pot life is defined as the time required for viscosity to double after Parts A and B (base and curing agent) are mixed and is highly temperature and application dependent. Please refer to the data table.

USEFUL TEMPERATURE RANGES

For most uses, silicone elastomers should be operational over a temperature range of -45 to 200°C (-49 to 392°F) for long periods of time. However, at both the low- and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations. For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

COMPATIBILITY

Certain materials, chemicals, curing agents and plasticizers can inhibit the cure of addition cure adhesives. Most notable of these include: Organotin and other organometallic compounds, Silicone rubber containing organotin catalyst, Sulfur, polysulfides, polysulfones or other sulfur containing materials, unsaturated hydrocarbon plasticizers, and some solder flux residues. If a substrate or material is questionable with respect to potentially causing inhibition of cure, it is recommended that a small scale compatibility test be run to ascertain suitability in a given application. The presence of liquid or uncured product at the interface between the questionable substrate and the cured gel indicates incompatibility and inhibition of cure.

REPAIRABILITY

In the manufacture of electrical/electronic devices it is often desirable to salvage or reclaim damaged or defective units. With most non-silicone rigid potting/encapsulating materials, removal or entry is difficult or impossible without causing excessive damage to internal circuitry. Dow Corning silicone encapsulants can be selectively removed with relative ease, any repairs or changes accomplished, and the repaired area reotted in place with additional product. To remove silicone elastomers, simply cut with a sharp blade or knife and tear and remove unwanted material from the area to be repaired. Sections of the adhered elastomer are best removed from substrates and circuitry by mechanical action such as scraping or rubbing and can be assisted by applying Dow Corning® brand OS Fluids. Before applying additional encapsulant to a repaired device, roughen the exposed surfaces of the cured encapsulant with an abrasive paper and rinse with a suitable solvent. This will enhance adhesion and permit the repaired material to become an integral matrix with the existing encapsulant. Silicone prime

coats are not recommended for adhering products to themselves.

PACKAGING

In general, Dow Corning silicone 1:1 mix ratio encapsulants are supplied in nominal 0.45-, 3.6-, 18- and 200-kg (1-, 8-, 40- and 440-lb) containers, net weight. Dow Corning silicone 10:1 mix ratio encapsulants are supplied in nominal 0.5-, 5-, 25- and 225-kg (1.1-, 11-, 55- and 495-lb) containers, net weight. Packaging options may vary by product. Consult Dow Corning Customer Service at (989) 496-6000 for additional packaging options.

STORAGE AND SHELF LIFE

Shelf life is indicated by the "Use Before" date found on the product label. For best results, Dow Corning silicone encapsulants should be stored at or below 25°C (77°F). Special precautions must be taken to prevent moisture from contacting these materials. Containers should be kept tightly closed and head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen.

HEALTH AND ENVIRONMENTAL INFORMATION

To support customers in their product safety needs, Dow Corning has an extensive Product Stewardship organization and a team of Product Safety and Regulatory Compliance (PS&RC) specialists available in each area. For further information, please see our website, www.dowcorning.com, or consult your local Dow Corning representative.

LIMITATIONS

These products are neither tested nor represented as suitable for medical or pharmaceutical uses.

LIMITED WARRANTY INFORMATION PLEASE READ CAREFULLY

The information contained herein is offered in good faith and is believed to be accurate. However, because conditions and methods of use of our products are beyond our control, this information should not be used in substitution for customer's tests to ensure that Dow Corning's products are safe, effective, and fully satisfactory for the intended end use. Suggestions of use shall not be taken as inducements to infringe any patent. Dow Corning's sole warranty is that the product will meet the Dow Corning sales specifications in effect at the time of shipment. Your exclusive remedy for breach of such warranty is limited to refund of purchase price or replacement of any product shown to be other than as warranted. DOW CORNING SPECIFICALLY DISCLAIMS ANY OTHER EXPRESS OR IMPLIED WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR MERCHANTABILITY. DOW CORNING DISCLAIMS LIABILITY FOR ANY INCIDENTAL OR CONSEQUENTIAL DAMAGES.

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For More Information

To learn more about these and other products available from Dow Corning, please visit the Dow Corning Electronics website at www.dowcorning.com/electronics.



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